



HI6718

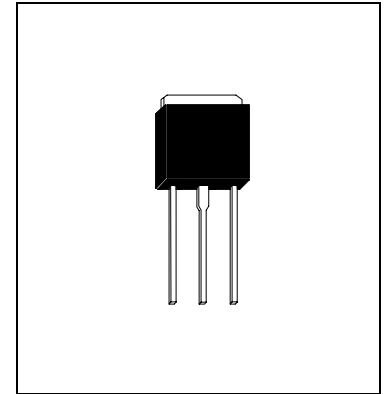
NPN EPITAXIAL PLANAR TRANSISTOR

Description

The HI6718 is designed for general purpose medium power amplifier and switching.

Features

- High power: 1.2W
- High current: 1A



Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
 Storage Temperature -55 ~ +150 °C
 Junction Temperature +150 °C
- Maximum Power Dissipation
 Total Power Dissipation (Tc=25°C) 20 W
- Maximum Voltages and Currents
 BVCBO Collector to Base Voltage 100 V
 BVCEO Collector to Emitter Voltage 100 V
 BVEBO Emitter to Base Voltage 5 V
 IC Collector Current 1 A

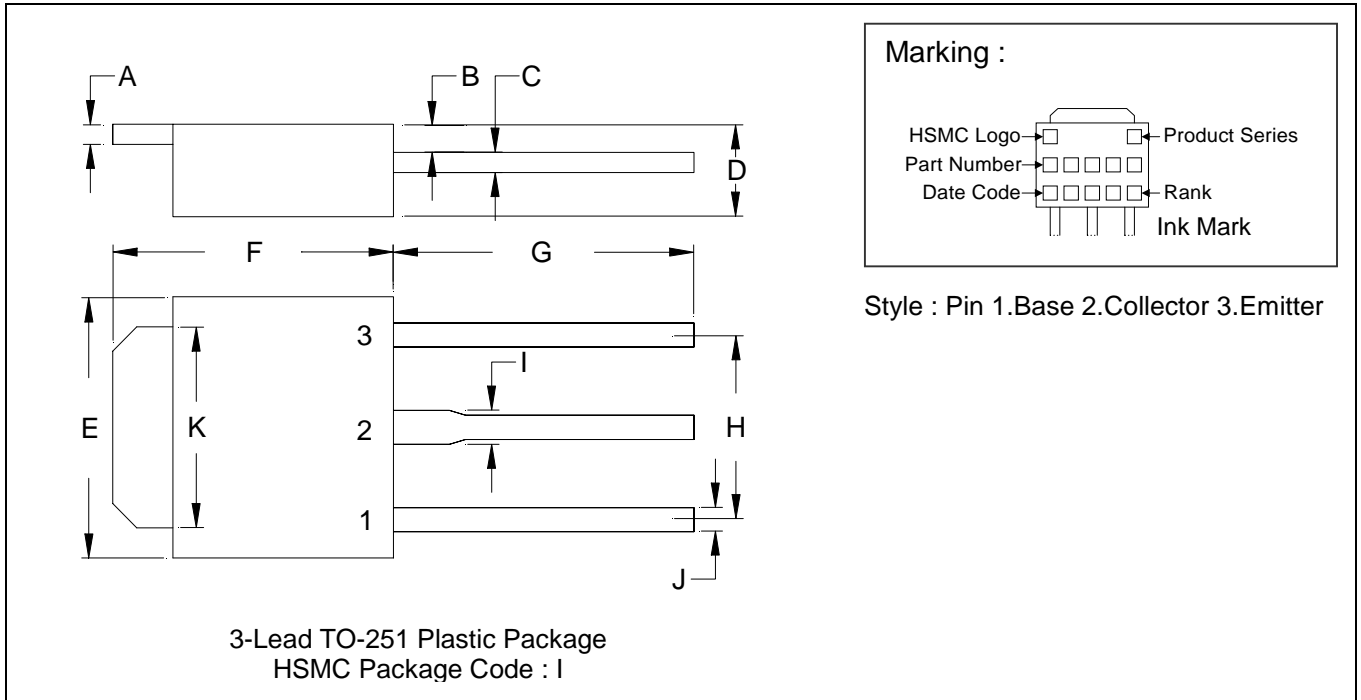
Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	100	-	-	V	IC=100uA
BVCEO	100	-	-	V	IC=1mA
BVEBO	5	-	-	V	IC=10uA
ICBO	-	-	100	nA	VCB=80V
*VCE(sat)	-	-	350	mV	IC=350mA, IB=35mA
*hFE1	80	-	-		VCE=1V, IC=50mA
*hFE2	50	-	250		VCE=1V, IC=250mA
*hFE3	20	-	-		VCE=1V, IC=500mA
fT	50	-	-	MHz	VCE=10V, IC=50mA, f=100MHz
Cob	-	-	20	pF	VCB=10V, f=1MHz

*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%



TO-251 Dimension



*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0177	0.0217	0.45	0.55	G	0.2559	-	6.50	-
B	0.0354	0.0591	0.90	1.50	H	-	*0.1811	-	*4.60
C	0.0177	0.0236	0.45	0.60	I	-	0.0354	-	0.90
D	0.0866	0.0945	2.20	2.40	J	-	0.0315	-	0.80
E	0.2520	0.2677	6.40	6.80	K	0.2047	0.2165	5.20	5.50
F	0.2677	0.2835	6.80	7.20					

Notes : 1.Dimension and tolerance based on our Spec. dated May. 24,1995.
 2.Controlling dimension : millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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